



SOT619-26(D)

HVQFN48, thermal enhanced very thin quad flat package, no leads, 48 terminals, 0.1 mm dimple wettable flank, 0.5 mm pitch, 7 mm x 7 mm x 0.85 mm body

4 March 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN48
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	22-01-2021
Manufacturer package code	98ASA01404D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	6.9	7	7.1	mm
package width	6.9	7	7.1	mm
package height	0.8	0.85	1	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	48	-	



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2 Package outline

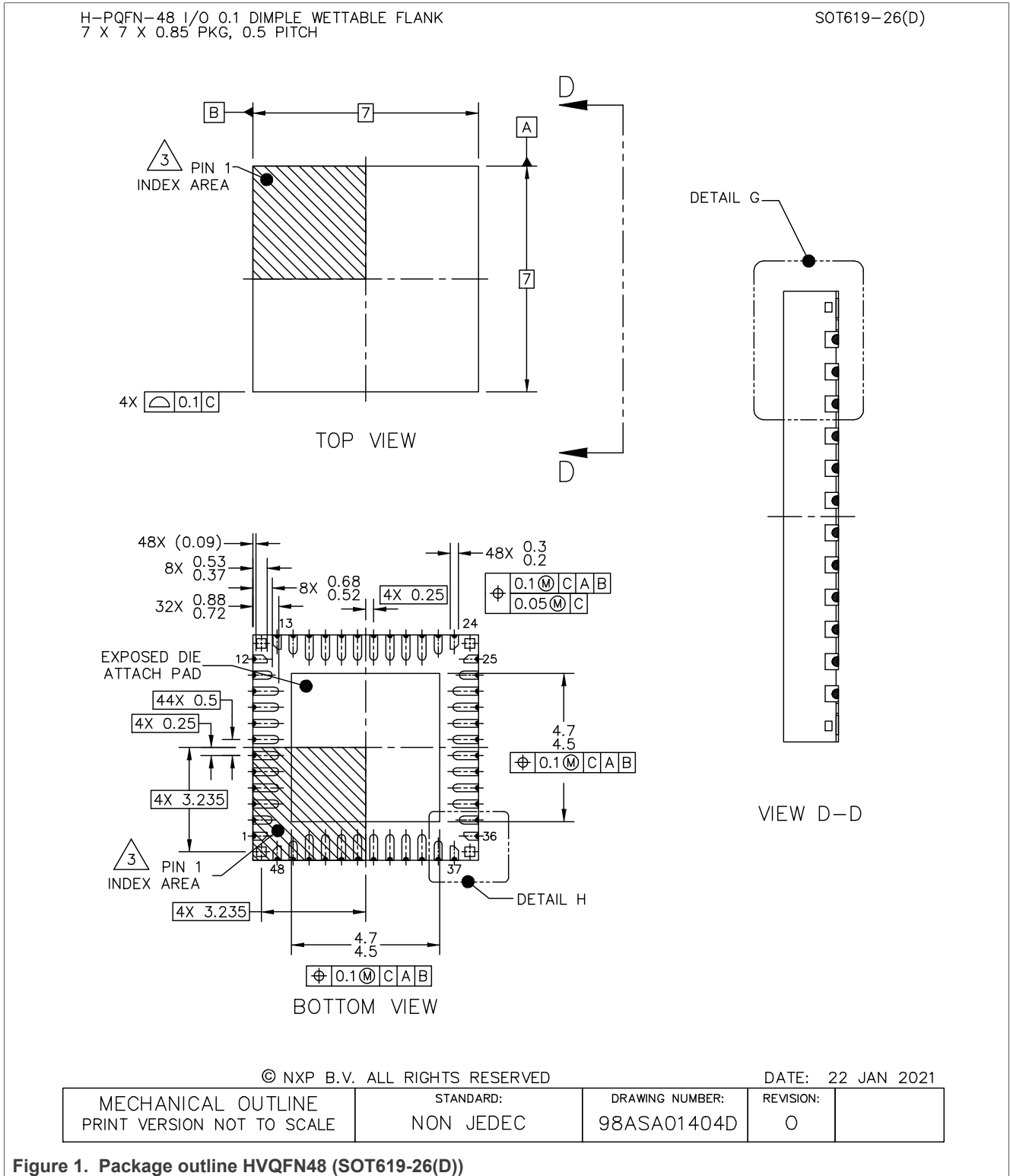


Figure 1. Package outline HVQFN48 (SOT619-26(D))

HVQFN48, thermal enhanced very thin quad flat package, no leads, 48 terminals, 0.1 mm dimple wettable flank, 0.5 mm pitch, 7 mm x 7 mm x 0.85 mm body

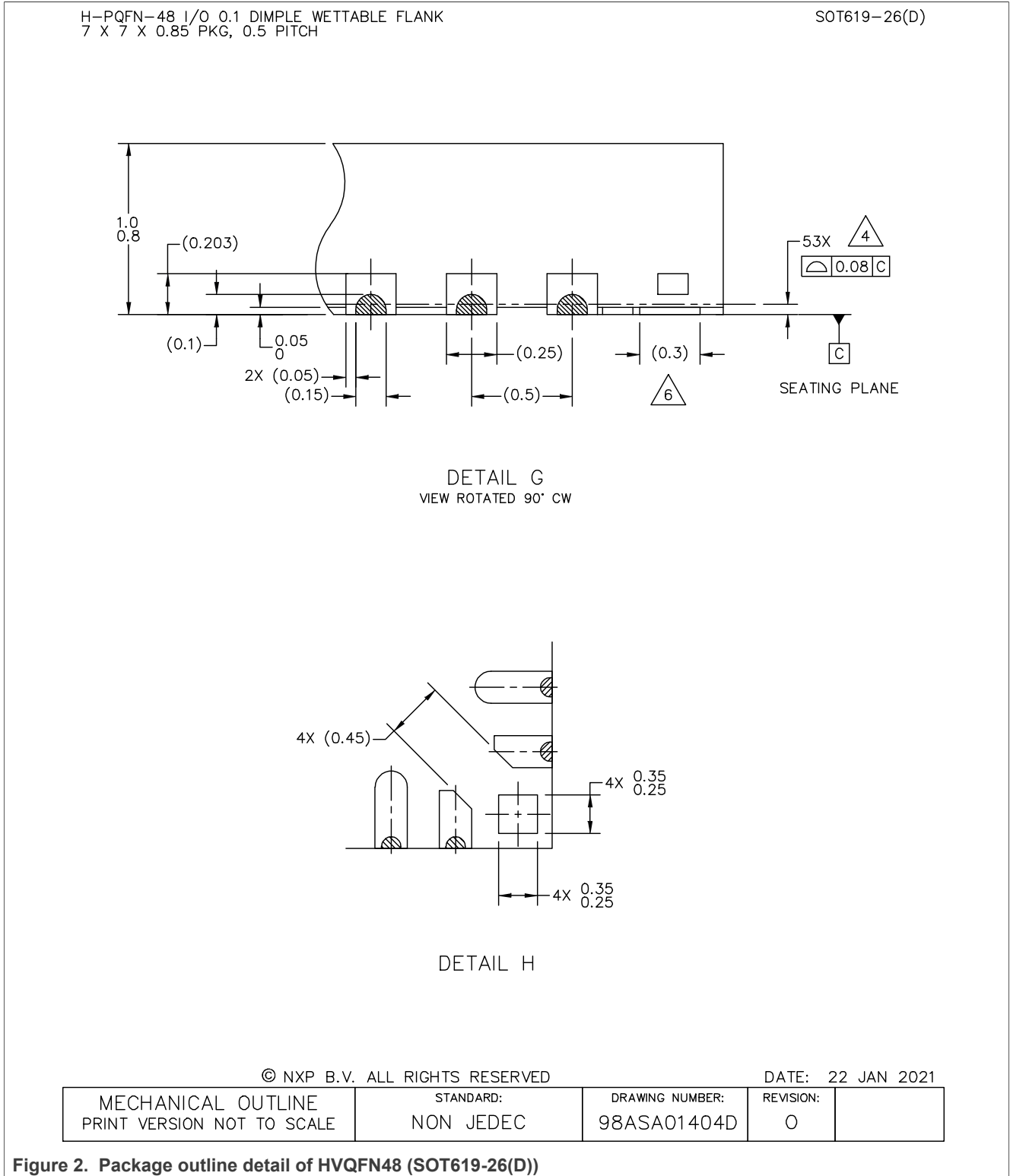
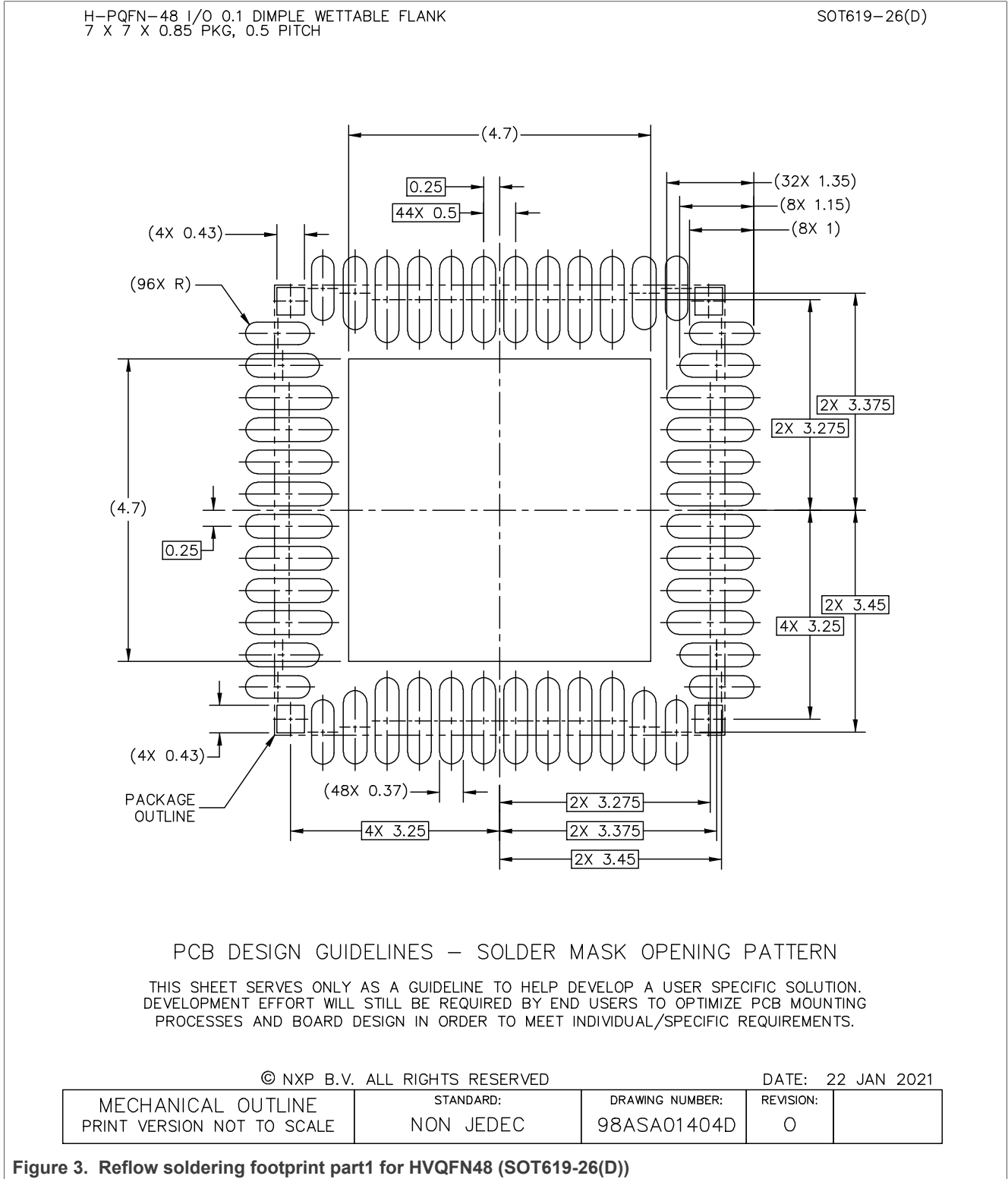


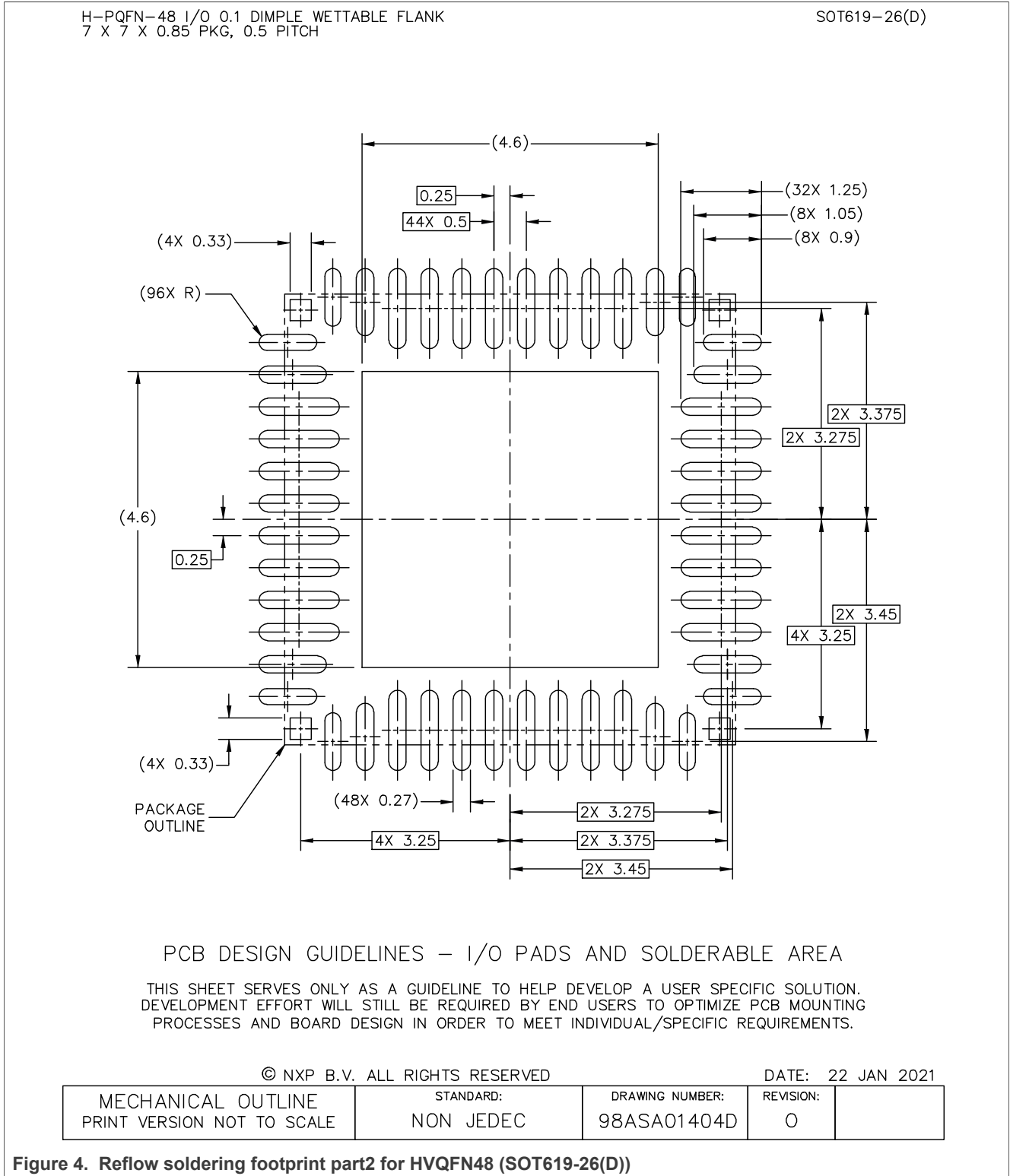
Figure 2. Package outline detail of HVQFN48 (SOT619-26(D))

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3 Soldering



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H-PQFN-48 I/O 0.1 DIMPLE WETTABLE FLANK
7 X 7 X 0.85 PKG, 0.5 PITCH

SOT619-26(D)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE, SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH PAD AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.25 MM.
6. ANCHORING PADS.

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DATE: 22 JAN 2021

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01404D	REVISION: 0	
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Figure 6. Package outline note HVQFN48 (SOT619-26(D))

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4 Legal information

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